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RESPONSE UNDER RULE 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP: 2814  
BOX AF

#(A)  
23E  
1431/2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MIURA, et al.  
Serial No.: 09/254,939  
Filed: March 17, 1999  
For: METHOD OF FABRICATING SEMICONDUCTOR DEVICE  
HAVING TRENCH ELEMENT SEPARATION STRUCTURE  
Group: 2814  
Examiner: Anh D. Mai

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents  
Washington, D.C. 20231  
BOX AF

December 2, 2002

RECEIVED  
DEC - 5 2002  
TC 2800 MAIL ROOM

Sir:

In response to the Office Action mailed July 30, 2002, please amend the  
above-identified application as follows:

IN THE CLAIMS

Please cancel claims 14 and 40 without prejudice or disclaimer, and amend  
the claims remaining in the application as follows:

1. (Four Times Amended) A method of fabricating a semiconductor  
device comprising the steps of:
- forming an oxidation prevention film on a circuit formation surface of a